

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
I_{PP}	Peak Current ($t_p=8/20\mu s$)	2.0	A
T_{OP}	Operating Temperature	-40 to 150	°C
T_{STOR}	Storage Temperature	-55 to 150	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the component. This is a stress only rating and operation of the component at these or any other conditions above those indicated in the operational sections of this specification is not implied.

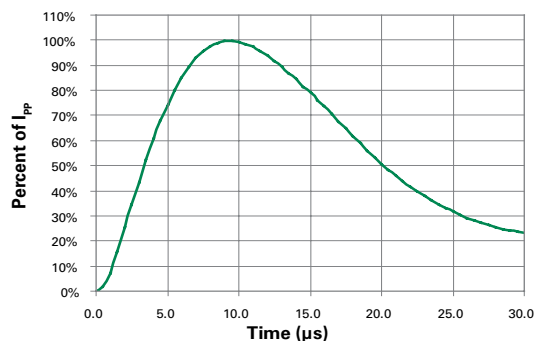
Electrical Characteristics ($T_{OP}=25^\circ C$)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Breakdown Voltage	V_{BR}	$I_R=1mA$	20		30	V
Reverse Standoff Voltage	V_{RWM}				18	V
Reverse Leakage Current	I_{LEAK}	$V_R=18V$ with 1 pin at GND		1	50	nA
Clamp Voltage ¹	V_C	$I_{PP}=1A$, $t_p=8/20\mu s$, Fwd		31	35	V
		$I_{PP}=2A$, $t_p=8/20\mu s$, Fwd		34	38	V
ESD Withstand Voltage ¹	V_{ESD}	IEC 61000-4-2 (Contact)	±10			kV
		IEC 61000-4-2 (Air)	±15			kV
Dynamic Resistance ²	R_{DYN}	TLP, $t_p=100ns$, I/O to GND		0.75		Ω

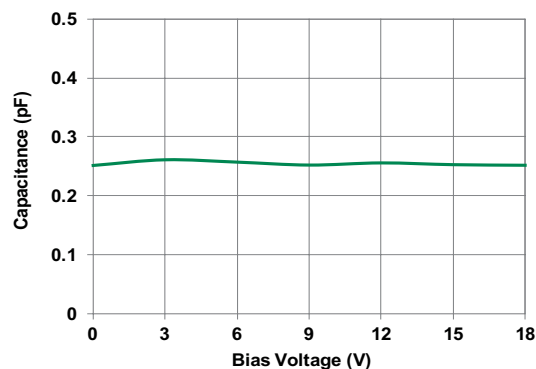
Note: 1. Parameter is guaranteed by design and/or component characterization.

2. Transmission Line Pulse (TLP) with 100ns width, 2ns rise time, and average window $t_1=70ns$ to $t_2=90ns$

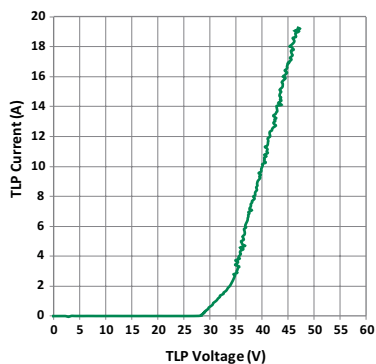
8/20 μs Pulse Waveform



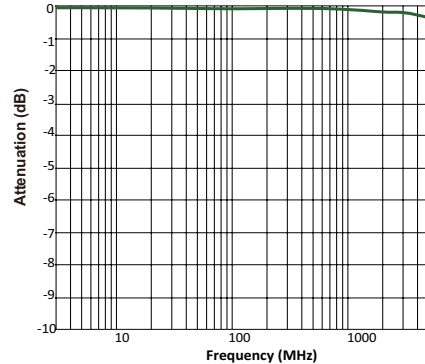
Capacitance vs. Reverse Bias



Transmission Line Pulsing (TLP) Plot

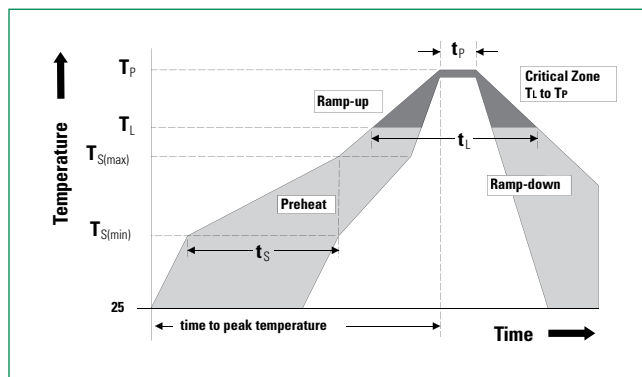


Insertion Loss (S21)

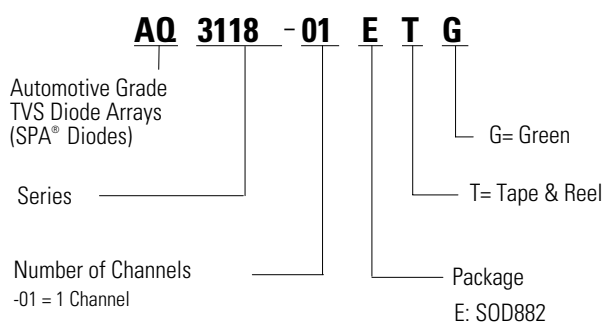


Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



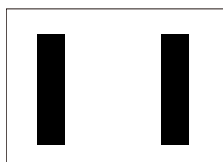
Part Numbering System



Product Characteristics

Lead Plating	Pre-Plated Frame
Lead Material	Copper Alloy
Substrate material	Silicon
Body Material	Molded Compound
Flammability	UL Recognized compound meeting flammability rating V-0

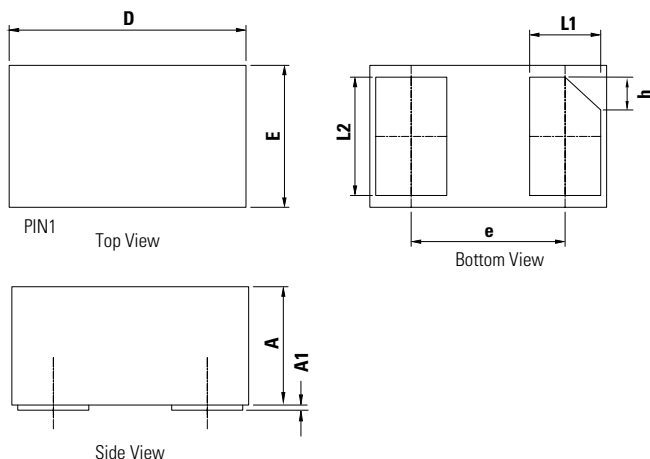
Part Marking System



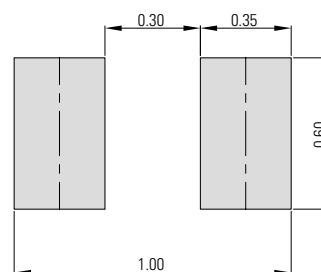
Ordering Information

Part Number	Package	Min. Order Qty.
AQ3118-01 ETG	SOD882	10000

Package Dimensions — SOD882

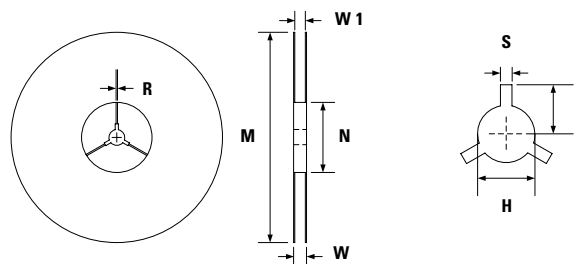
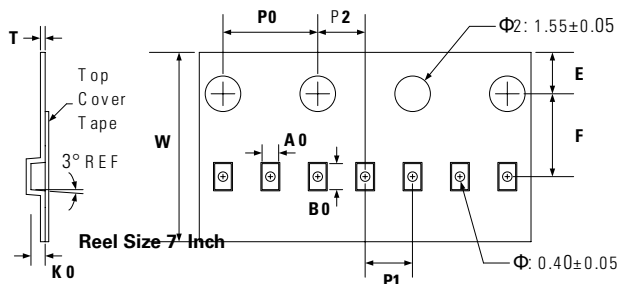


Symbol	Dimensions		
	Min	Nor.	Max
A	0.45	0.50	0.55
A1	0.00	0.02	0.05
L1	0.20	0.25	0.30
L2	0.45	0.50	0.55
D	0.95	1.00	1.05
E	0.55	0.60	0.65
e	0.65BSC		
h	0.07	0.12	0.17



Recommended Soldering Pad Layout (mm)

Embossed Carrier Tape & Reel Specification — SOD882



Symbol	Tape Dimensions	
	Millimetres	
	Min	Max
A0	0.65	0.75
B0	1.10	1.20
K0	0.50	0.60
E	1.65	1.85
F	3.45	3.55
P0	3.90	4.10
P1	1.90	2.10
P2	1.95	2.05
T	1.95	2.05
W	7.90	8.10

Symbol	Reel Dimensions (Size Φ178)	
	Millimetres	
	Min	Max
M	177.0	179.0
N	59.0	61.0
W	11.0	12.0
W1	8.5	9.5
H	12.5	13.5
S	1.9	2.1
K	10.8	11.2
R	0.95	1.05

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